

## Universality of Impact Ionization Rate in 0.1 $\mu$ m Si MOSFET

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We investigated impact ionization in Si MOSFET's with the gates as short as 0.1 $\mu$ m at room temperature. The impact ionization rate falls on a simple straight line regardless of the gate voltage  $V_{gs}-V_{th}$  and the gate length  $L_g$  when  $\ln[I_{sub}/I_d(V_{ds}-V_{dsat})]$  is plotted versus  $1/(V_{ds}-V_{dsat})$  where  $V_{dsat}$  is the drain saturation voltage. However, we found a deviation from the universal relation, which depends on gate voltage. We clarified the origin of the deviation and present a new method for obtaining the universal plot.

### 1. Introduction

Impact ionization in deep submicron MOSFET's has been studied in conjunction with non-stationary transport such as velocity overshoot<sup>1),2)</sup>. The method used to characterize impact ionization rate in these studies is based on pseudo-two-dimensional model that describes the maximum channel electric field  $E_m$  near the drain junction. The electric field  $E_m$  is roughly proportional to  $V_{ds}-V_{dsat}$ , where  $V_{dsat}$  is the voltage at the point where the carrier velocity saturates. Hence the impact ionization rates defined by the ratio of substrate current to drain current  $I_{sub}/I_d$  fall on a simple straight line regardless of the gate voltage  $V_{gs}$  and the gate length  $L_g$ , when  $\ln(I_{sub}/I_d)$  is plotted versus  $1/(V_{ds}-V_{dsat})$ <sup>3)</sup>.

In this work, we investigated the impact ionization in deep submicron MOSFET's with the gate length  $L_g$  down to 0.1 $\mu$ m and found that such a universal straight line is not obtained for different  $V_{gs}$ . We clarified that the observed deviation dependent on  $V_{gs}$  is due to the difference in the saturation electric field  $E_{sat}$ , which is the channel electric field for the velocity saturation of electrons.

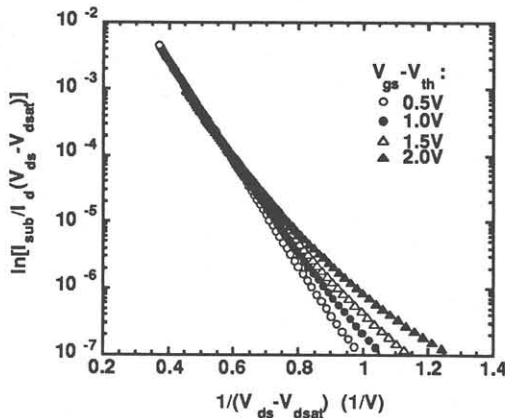
### 2. Experiments and Discussion

The two nMOSFET's used in this study (samples A and B) have LDD structures. Although the conditions of ion implantation for the channel and LDD are the same, the gate oxide thickness  $T_{ox}$  is different in these two samples (46Å for sample A and 32Å for sample B). Figure 1 shows the conventional plot  $\ln[I_{sub}/I_d(V_{ds}-V_{dsat})]$  versus  $1/(V_{ds}-V_{dsat})$  for an nMOSFET with  $L_g=0.15\mu$ m in sample A. We determined  $V_{dsat}$  using the method proposed by T.Chan et al., which is based on the idea that the loci of constant  $I_{sub}/I_d$  are parallel to the locus of  $V_{dsat}$  on the  $V_{ds}-I_d$  characteristics<sup>3)</sup>. One can find the deviation from the straight line for higher  $V_{gs}-V_{th}$  and/or lower  $V_{ds}-V_{dsat}$ . According to the analytical expression<sup>4)</sup>

$$I_{sub} = \frac{A_i}{B_i} I_{Em} I_d \exp\left[-\frac{B_i}{E_m}\right] \quad (1)$$

$I_{sub}$  is determined by the maximum electric field  $E_m$  at the drain edge. Hence the contribution of  $I_{sub}$  from other region leads to the increased impact ionization rate. However, the measured  $I_{sub}$  did not show any specific increase for the low  $E_m$  conditions where the deviation from the straight line occurs. In addition, similar

deviations were observed for all the investigated nMOSFET's with  $L_g=0.1\mu\text{m}$  to  $0.8\mu\text{m}$  in contrast to the result of T.Mizuno et al<sup>2)</sup>. Thus we cannot attribute the deviations to the enhanced electron temperature in short channel MOSFET's with  $L_g$  near  $0.1\mu\text{m}$ .



**Fig.1** Plot of  $\ln[I_{\text{sub}}/I_d(V_{\text{ds}}-V_{\text{dsat}})]$  versus  $1/(V_{\text{ds}}-V_{\text{dsat}})$  for the sample A with  $L_g=0.15\mu\text{m}$ . Measured for  $V_{\text{gs}}-V_{\text{th}}$  of 0.5V, 1.0V, 1.5V, and 2.0V.

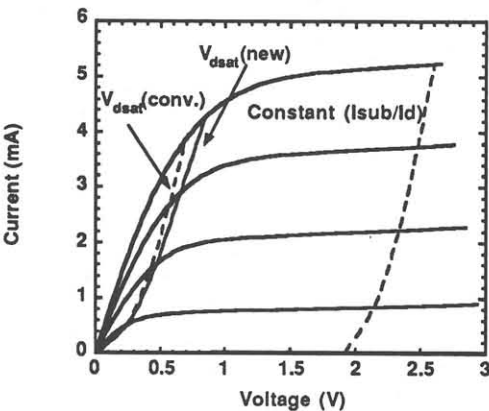
The pseudo-two-dimensional model describes  $E_m$  as

$$E_m = \sqrt{\frac{(V_{\text{ds}}-V_{\text{dsat}})^2}{l^2} + E_{\text{sat}}^2} \quad (2)$$

where  $l$  is the effective length of the velocity-saturation region<sup>3)</sup>. Usually the  $E_{\text{sat}}$  term in Eq.(2) is omitted and the universal relation between impact ionization rate and  $1/(V_{\text{ds}}-V_{\text{dsat}})$  is derived by introducing Eq.(2) into Eq.(1). In this case, we must include the  $E_{\text{sat}}$  term, because the deviation occurs for lower  $V_{\text{ds}}-V_{\text{dsat}}$ . We deduced the effective length  $l$  from the slope of the curve for  $V_{\text{gs}}-V_{\text{th}}=0.5\text{V}$  in Fig.1 and an empirical parameter  $B_i=1.7\times 10^6\text{V/cm}^3$ . However, a similar deviation as that in Fig.1 remains, if we introduce the constant  $E_{\text{sat}}=4\times 10^4\text{V/cm}$  proposed by T.Chan et al. into Eq.(2) for the plot of  $\ln[I_{\text{sub}}/(I_d\cdot E_m)]$  versus  $1/E_m$ <sup>3)</sup>.

To obtain straight lines, we must

consider  $E_{\text{sat}}$  as a fitting parameter and introduce a larger  $E_{\text{sat}}$  into Eq.(2) for the curve of higher  $V_{\text{gs}}-V_{\text{th}}$ . The conventional method to determine  $V_{\text{dsat}}$  becomes incorrect, because the loci of constant  $I_{\text{sub}}/I_d$  are not parallel to the locus of  $V_{\text{dsat}}$ . We deduced a new  $V_{\text{dsat}}$  for each  $V_{\text{gs}}-V_{\text{th}}$  from the measured  $V_{\text{ds}}$



**Fig.2**  $V_{\text{ds}}-I_d$  characteristics of a  $0.15\mu\text{m}$  nMOSFET for  $V_{\text{gs}}-V_{\text{th}}$  of 0.5V, 1.0V, 1.5V, and 2.0V. The locus of  $V_{\text{dsat}}(\text{conv.})$  is drawn parallel to that of constant  $I_{\text{sub}}/I_d$  according to the conventional method. The locus of  $V_{\text{dsat}}(\text{new})$  shows the new  $V_{\text{dsat}}$  determined by the method we propose in this work.

on a constant  $I_{\text{sub}}/I_d$  locus according to

$$V_{\text{dsat}} = V_{\text{ds}} - l\sqrt{C - E_{\text{sat}}^2} \quad (3)$$

where the constant  $C$  means  $E_m^2$  for  $V_{\text{gs}}-V_{\text{th}}=0.5\text{V}$ . As shown in Fig.2, the difference between the new  $V_{\text{dsat}}$  and the former ones increases with  $V_{\text{gs}}-V_{\text{th}}$ . Figure 3 shows the plot of  $\ln[I_{\text{sub}}/(I_d\cdot E_m)]$  versus  $1/E_m$ , where  $E_{\text{sat}}$  in Eq.(2) is considered to be a fitting parameter dependent on  $V_{\text{gs}}-V_{\text{th}}$ . One can find the recovery of universal relation. A similar procedure successfully recovered the universality in the plot for sample B which has a thinner gate oxide than sample A.

To confirm the validity of  $E_{\text{sat}}$  deduced by the fitting of curves in Fig.3, we performed a simple estimation of  $E_{\text{sat}}$  from the effective surface mobility  $\mu_{\text{eff}}$ . We deduced  $\mu_{\text{eff}}$  from the

measured channel conductance for a MOSFET with  $L_g=5\mu\text{m}$  fabricated on the same chip as the deep submicron MOSFET's we investigated, because the conductance of a long channel device is not affected by the parasitic resistance. We estimated  $E_{\text{sat}}$  by the empirical relation  $E_{\text{sat}}=2v_{\text{sat}}/\mu_{\text{eff}}$ , where  $v_{\text{sat}}$  is the saturation velocity of electrons. Although the reported values of  $v_{\text{sat}}$  scatter between  $4\times 10^6\text{cm/sec}$  and  $1\times 10^7\text{cm/sec}$  so far, we assumed  $v_{\text{sat}}$  to be  $7.0\times 10^6\text{cm/sec}$ . In Table1, we compared the results with  $E_{\text{sat}}$  obtained for a MOSFET with  $L_g=0.15\mu\text{m}$  in samples A and B by the fitting of impact ionization rate. The fairly good agreement of  $E_{\text{sat}}$  data supports that the deviation of the curves in Fig.1 is due to the gate voltage dependence of  $E_{\text{sat}}$ , which results from the degradation of mobility  $\mu_{\text{eff}}$  by the normal electric field.

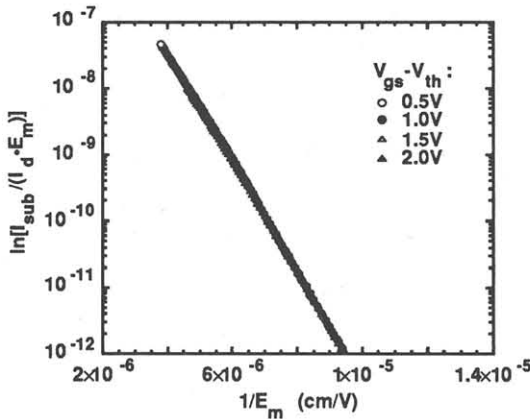


Fig.3 Plot of  $\ln[I_{\text{sub}}/(I_d \cdot E_m)]$  versus  $1/E_m$ . The measured data is same as Fig.1. The saturation electric field  $E_{\text{sat}}$  in the description of maximum channel electric field  $E_m$  is chosen to fit the curve for  $V_{\text{gs}}-V_{\text{th}}=0.5\text{V}$ . The resulting change in  $V_{\text{dsat}}$  is also introduced.

### 3. Conclusion

For nMOSFET's with thin gate oxides, the universal relation is not obtained using the simple plot  $\ln[I_{\text{sub}}/I_d(V_{\text{ds}}-V_{\text{dsat}})]$  versus  $1/(V_{\text{ds}}-V_{\text{dsat}})$  and the conventional method to determine  $V_{\text{dsat}}$ . Universality can be restored by considering  $E_{\text{sat}}$  as a parameter dependent on the gate voltage, and modifying  $V_{\text{dsat}}$  for the

description of maximum channel electric field  $E_m$ . The fitted  $E_{\text{sat}}$  for the recovery of universality agrees quite well with the estimated  $E_{\text{sat}}$  from the empirical relation for the  $v$ - $E$  curve and the measured effective mobility  $\mu_{\text{eff}}$ . These results show that the pseudo-two-dimensional model is still useful for describing the maximum channel electric field  $E_m$  in deep submicron MOSFET's with gates as short as  $0.1\mu\text{m}$ .

$V_{\text{gs}}-V_{\text{th}}$	1.0V	1.5V	2.0V
$E_{\text{sat}}(\text{f})[\text{A}]$	$6\times 10^4$	$7\times 10^4$	$8.5\times 10^4$
$E_{\text{sat}}(\mu)[\text{A}]$	$5.8\times 10^4$	$6.6\times 10^4$	$7.7\times 10^4$
$E_{\text{sat}}(\text{f})[\text{B}]$	$6\times 10^4$	$7.5\times 10^4$	$9\times 10^4$
$E_{\text{sat}}(\mu)[\text{B}]$	$6.1\times 10^4$	$7.6\times 10^4$	$9.6\times 10^4$

Table 1 The saturation electric field  $E_{\text{sat}}$  data obtained by the fitting are denoted by  $E_{\text{sat}}(\text{f})$ . Those estimated with the effective mobility  $\mu_{\text{eff}}$  are denoted by  $E_{\text{sat}}(\mu)$ . These  $E_{\text{sat}}$  data are compared for each  $V_{\text{gs}}-V_{\text{th}}$  in samples A and B with  $L_g=0.15\mu\text{m}$ .

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